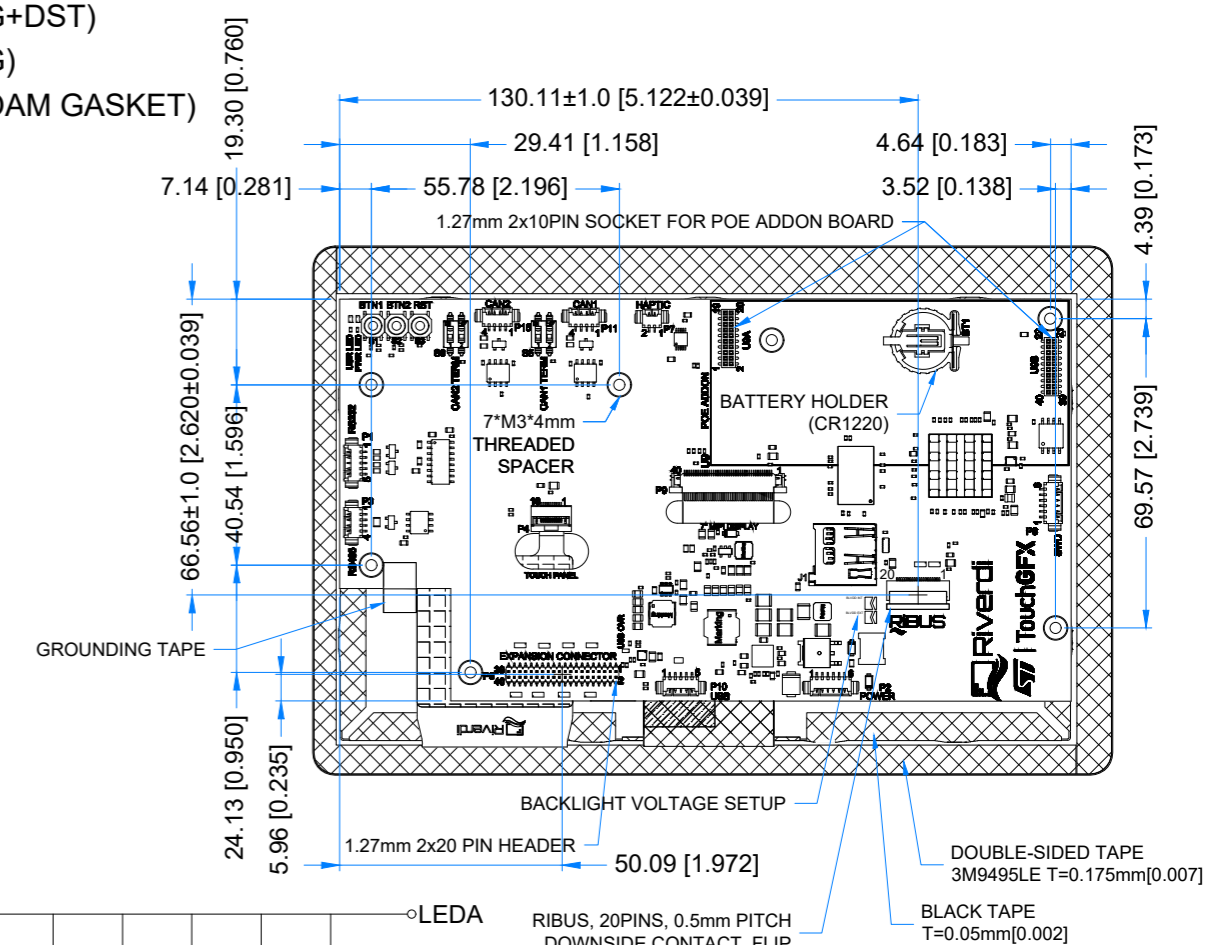
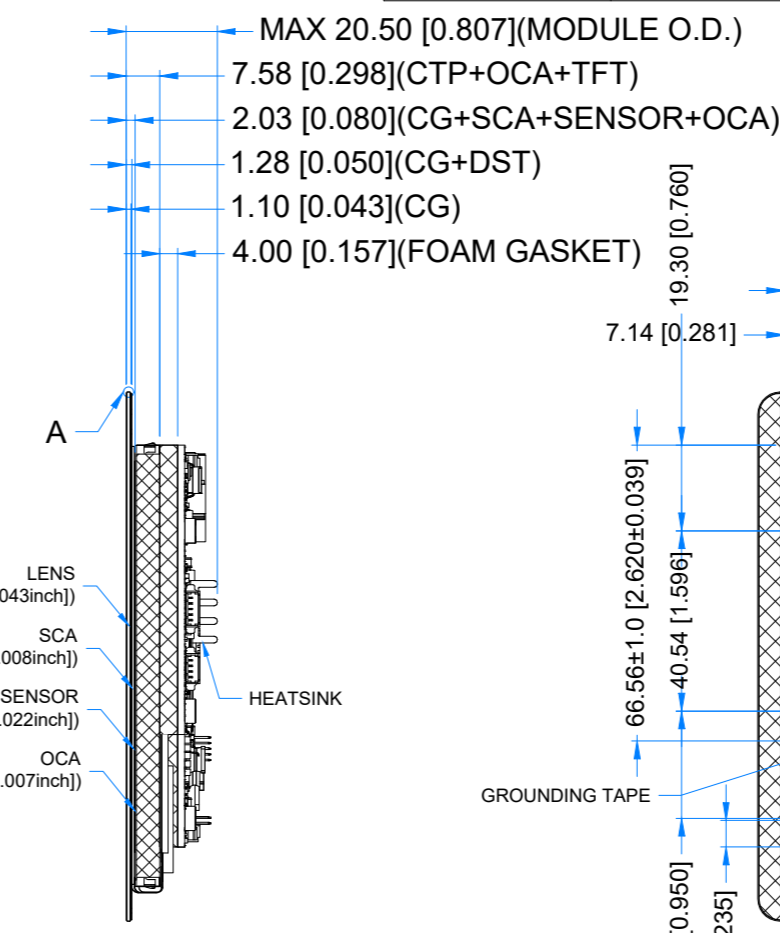
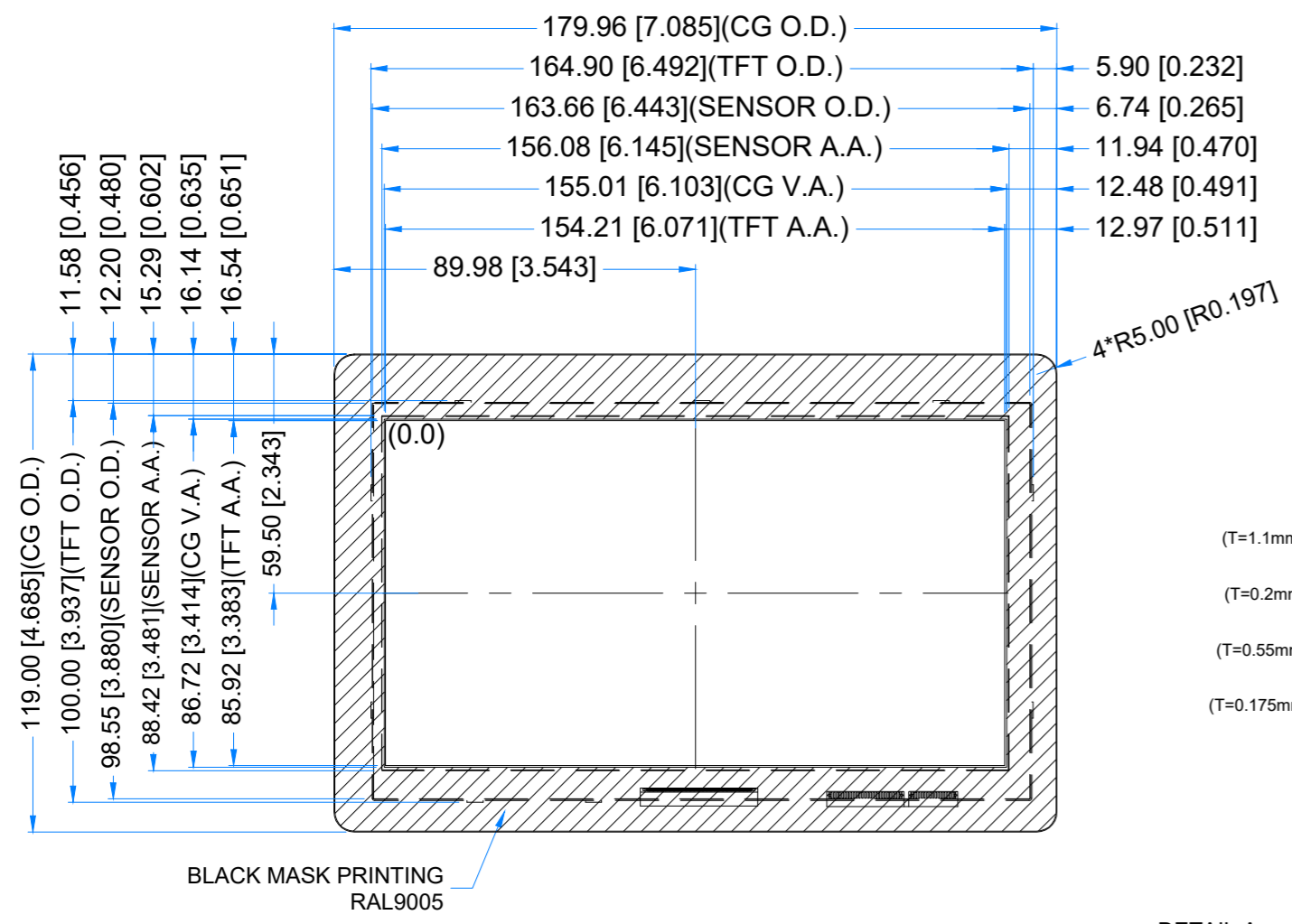
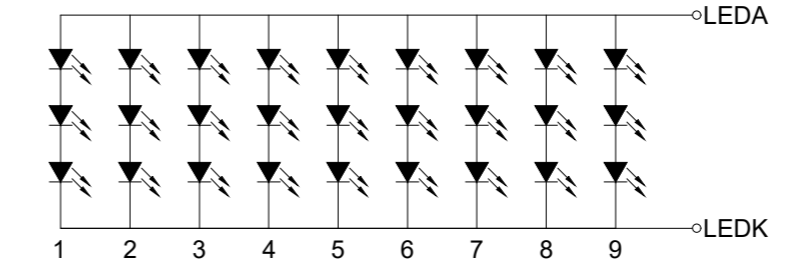
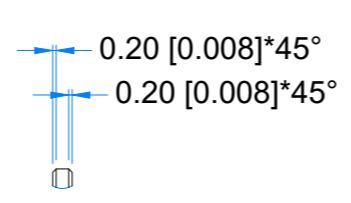


Revision:	Changes:	Date:
1.0	Initial Case	2022.04.05
1.1	Added Heatsink And Dimensions Overhaul	2022.07.12
1.2	PCB Update - 70STM32H7_Rev1.2	2022.11.02
1.3	PCB Update - 70STM32H7_Rev1.3	2024.07.04



DETAIL A
SCALE 4:1



LED DIAGRAM CIRCUIT

1.27MM PIN HEADER AND SOCKET

NO.	TYPE	MATE WITH
P8	CH51402M100-0P	CBC1402D100 OR CBC1402M100-2P
U9a & U9b	PBHTD20SPP	CH51202V100 OR CH51202M100-0P

1.25 MM MOLEX CONNECTORS

NO.	TYPE	MATE WITH
P1 (RS232)	53261-0571	51021-0500
P2 (POWER)	53261-0671	51021-0600
P3 (RS485)	53261-0471	51021-0400
P6 (SWD)	53261-0671	51021-0600
P7 (HAPTIC)	53261-0271	51021-0200
P10 (USB)	53261-0571	51021-0500
P11 (CAN1)	53261-0471	51021-0400
P15 (CAN2)	53261-0471	51021-0400

TFT NOTES:
1. DISPLAY TYPE: TRANSMISSIVE, NORMALLY BLACK, IPS
2. RESOLUTION: 1024x600
3. VIEWING ANGLE: FREE
4. SURFACE LUMINANCE: 850 cd/m²
5. MCU ON THE BOARD: STM32H757XIH6
6. EXTERNAL FLASH MEMORY SIZE: 512Mbit
7. EXTERNAL SDRAM SIZE: 64Mbit (32-bit access)
8. SUPPLY VOLTAGE FOR MODULE: 6.0V - 48.0V

TP NOTES:
1. TP STRUCTURE: G+G
2. CG THICKNESS: 1.10mm[0.043inch]
3. SURFACE HARDNESS: 7H
4. DRIVER IC: ILI2132A
5. INTERFACE: CONNECTED TO MCU VIA I2C

GENERAL NOTES:
1. OPTICAL BONDING
2. OPERATING TEMPERATURE: -20°C ~ 70°C
3. STORAGE TEMPERATURE: -30°C ~ 80°C
4. WITHOUT INDIVIDUAL TOLERANCE:
±0.3mm[0.012inch]
5. TOLERANCE OF PCB PLACEMENT:
±0.5mm[0.020inch]
6. RoHS3 COMPLIANT

PN: RVT70HSSNWC00-B
SN:
DRAWN: M.Natywa 2024.07.04 1:1.70
CHECKED: M.Wierzbowski 2024.07.04 [mm]
APPR: T.Soldat 2024.07.04 ISO A3 P. 1 of 1

